

L Number	Hits	Search Text	DB	Time stamp
-	51211	((metal or metallic or copper or sink or spreader) with substrate) and (chip or die or chips or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:12
-	15634	((metal or metallic or copper or sink or spreader) with substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:07
-	9376	((metal or metallic or copper or sink or spreader) with substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:14
-	10517	((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 12:10
-	3581	((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:13
-	2021	((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:02
-	1721	((metal or metallic or copper or sink or spreader) near substrate) and (chip or die or chips or dies)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:07
-	1008	257/758.ccls. and ((metal or metallic or copper or sink or spreader) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 12:59
-	148	257/758.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:04
-	27	(257/758.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 12:59
-	17	((257/758.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (dice or singulate or singulating or cut or saw)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:00
-	89	438/618.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:06
-	76	(438/618.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:01

-	7	((438/618.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (@ad<20011231)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:04
-	0	438/198.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:07
-	98	438/622.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:08
-	46	"L163" and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:07
-	86	(438/622.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:08
-	7	((438/622.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (@ad<20011231)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:08
-	55	438/98.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:08
-	55	(438/98.ccls. and ((metal or metallic or copper or cu or sink or spreader) near substrate)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:08
-	4130	((metal or metallic or steel) near substrate) and (chips or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:01
-	1683	((((metal or metallic or steel) near substrate) and (chips or dies)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:01
-	1463	(((((metal or metallic or steel) near substrate) and (chips or dies)) and (dice or singulate or singulating or cut or saw)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 13:14
-	789	(((((metal or metallic or steel) near substrate) and (chips or dies)) and (dice or singulate or singulating or cut or saw)) and (@ad<20011231)) and (dielectric or insulate or insulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:00
-	18	("4630096"   "4714516"   "4783695"   "4827328"   "4835704"   "4860166"   "4866508"   "4878991"   "4884122"   "4894115"   "4901136"   "4907062"   "4918811"   "4933042"   "5049980"   "5065282"   "5091769"   "5111278").PN.	USPAT	2003/10/24 13:50
-	18	("4630096"   "4714516"   "4783695"   "4827328"   "4835704"   "4860166"   "4866508"   "4878991"   "4884122"   "4894115"   "4901136"   "4907062"   "4918811"   "4933042"   "5049980"   "5065282"   "5091769"   "5111278").PN.	USPAT	2003/10/24 13:53

-	18	("4630096"   "4714516"   "4783695"   "4827328"   "4835704"   "4860166"   "4866508"   "4878991"   "4884122"   "4894115"   "4901136"   "4907062"   "4918811"   "4933042"   "5049980"   "5065282"   "5091769"   "5111278").PN.	USPAT	2003/10/24 13:54
-	56	5250843.URPN.	USPAT	2003/10/24 13:54
-	413	((metal or metallic or steel) near wafer) and (chips or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:01
-	361	((metal or metallic or steel) near wafer) and (chips or dies)) and (@ad<20011231)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:01
-	190	((metal or metallic or steel) near wafer) and (chips or dies)) and (@ad<20011231)) and (dice or singulate or singulating or cut or saw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:02
-	124	((metal or metallic or steel) near wafer) and (chips or dies)) and (@ad<20011231)) and (dice or singulate or singulating or cut or saw)) and (dielectric or insulate or insulating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/24 14:02